

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the applications:

Listing of Claims:

Claims 1-20 (canceled)

Claim 21 (New) A system for polishing process in fabricating semiconductor devices, said system comprising:

a plurality types of polishing module arranging in an arbitrary sequence beginning with a first polishing module and ending with a last polishing module;

means for transferring a substrate between said polishing modules;

an unload station for unloading said substrate from said transferring means after ending polishing at said last polishing module; and

a load station for loading said transferring means with said substrate prior to starting polishing at said first polishing module.

Claim 22 (New) The system according to claim 21, wherein said plurality types of polishing modules comprises two types of polishing modules.

Claim 23 (New) The system according to claim 21, wherein said plurality types of polishing modules comprises three types of polishing modules.

Claim 24 (New) The system according to claim 21, wherein said plurality types of polishing modules comprises four types of polishing modules.

Claim 25 (New) The system according to claim 21, wherein said plurality types of polishing modules comprises a rotary chemical mechanical polisher, an orbital chemical mechanical polisher, a fixed-abrasive chemical mechanical polisher, and a linear chemical mechanical polisher.

Claim 26 (New) The system according to claim 21, wherein said polishing modules comprises:

a polishing surface;

a movable substrate carrier for holding said substrate being positionable over said polishing surface, wherein at least one of said polishing surface and said substrate carrier moves with respect to the other to impart relative motion between said substrate and said polishing surface; and

a liquid solution dispenser for dispensing a polishing solution on said polishing surface.

Claim 27 (New) The system according to claim 21, wherein said transferring means comprises a plurality of carrier heads for holding said substrate.

Claim 28 (New) The system according to claim 21, further comprising a controller for controlling movements of said transferring means.

Claim 29 (New) The system according to claim 21, further comprising a cleaner for cleaning said substrate.

Claim 30 (New) A system for polishing process in fabricating semiconductor devices, said system comprising:

a plurality types of polishing modules arranging in an arbitrary sequence beginning with a first polishing module and ending with a last polishing module, wherein said plurality type of polishing modules have different polishing processes and are individually independent;

means for transferring said substrate between said polishing modules;

an unload station for unloading said substrate from said transferring means after ending polishing at said last polishing module; and

a load station for loading said transferring means with said substrate prior to starting polishing at said first polishing module.

Claim 31(New) The system according to claim 30, wherein said plurality types of polishing modules can be three polishing modules.

Claim 32 (New) The system according to claim 31, wherein the combination of said three polishing modules can be each of a different type.

Claim 33 (New) The system according to claim 31, wherein the combination of said three polishing modules can be just two types, one type with two identical polishers arranged in an arbitrary sequence beginning with said first polishing module and ending with said last polishing module.

Claim 34 (New) The system according to claim 31, wherein said three polishing modules can apply to shallow trench isolation polishing process.

Claim 35 (New) The system according to claim 31, wherein said plurality types of polishing module comprises four polishing modules, wherein said four polishing modules can be each of a different type.

Claim 36 (New) The system according to claim 35, wherein said four polishing modules can be classified in two types, wherein each types with two identical polisher.

Claim 37 (New) The system according to claim 35, wherein said four polishing modules can be classified in three types, wherein one type with two identical polishers.

Claim 38 (New) The system according to claim 35, wherein said four polishing modules apply to a copper layer polishing process.

Claim 39 (New) The system according to claim 30, wherein said polishing modules comprises:

a polishing surface;

a movable substrate carrier for holding said substrate being positionable over said polishing surface, wherein at least one of said polishing surface and said movable substrate carrier moves with respect to the other to impart relative motion between said substrate and said polishing surface; and

a liquid solution dispenser for dispensing a polishing solution on said polishing surface.

Claim 40 (New) The system according to claim 30, wherein said transferring means comprises a plurality of carrier heads for holding said movable substrate.

Claim 41 (New) The system according to claim 30, wherein said plurality types of polishing modules comprises a rotary chemical mechanical polisher, an orbital chemical mechanical polisher, a fixed-abrasive chemical mechanical polisher, and a linear chemical mechanical polisher.

Claim 42 (New) The system according to claim 30, further comprising a controller for controlling movements of said transferring means.

Claim 43 (New) The system according to claim 30, further comprising a cleaner for cleaning said substrate.